IN THE CLAIMS

1. (currently amended) A fluid ejection method for selectively depositing fluid on printing media, the method comprising:

providing a carrier configured to receive a fluid ejecting substrate, the fluid ejecting substrate comprising an orifice layer, first planar surface and a contact surface positioned below the first planar surface;

inserting the fluid ejecting substrate into the carrier;

forming an electrical coupling between the contact surface of the fluid ejecting substrate and the carrier; and

providing a mold for dispensing an encapsulant on top of the electrical coupling to form a substantially co-planar surface with an upper surface of the fluid ejecting substrate and an upper surface of the carrier that faces in the same direction as the upper surfaces of the fluid ejecting substrate and the carrier.

2. (original) The method of claim 1 further comprising dispensing the encapsulant through the mold while the mold is positioned over the fluid ejecting substrate.

3. (original) The method of claim 1 further comprising controlling positioning of the encapsulant once the encapsulant has been dispensed onto a predetermined portion of the fluid ejecting substrate.

4. (original) The method of claim 1 further comprising removing the mold once the positioning of encapsulant is complete.